

LNPT[™] THERMOCOMP[™] COMPOUND AX02749

PDX-A-02749

DESCRIPTION

LNP THERMOCOMP AX02749 compound is based on Acrylonitrile Butadiene Styrene (ABS) resin containing 20% glass fiber.

GENERAL INFORMATION	
Features	High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Acrylonitrile Butadiene Styrene (ABS)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break, 5 mm/min	77	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.8	%	ISO 527
Tensile Modulus, 1 mm/min	6040	MPa	ISO 527
Flexural Stress	119	MPa	ISO 178
Flexural Modulus, 2 mm/min	5970	MPa	ISO 178
Tensile Stress, brk, Type I, 5 mm/min	76	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2	%	ASTM D638
Tensile Modulus, 50 mm/min	6080	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	122	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	6080	MPa	ASTM D790
IMPACT ⁽¹⁾			
Izod Impact, notched 80*10*4 +23°C	7	kJ/m ²	ISO 180/1A
Izod Impact, unnotched 80*10*4 +23°C	23	kJ/m ²	ISO 180/1U
Multiaxial Impact	2	J	ISO 6603
Izod Impact, notched, 23°C	80	J/m	ASTM D256
Izod Impact, unnotched, 23°C	374	J/m	ASTM D4812
Instrumented Dart Impact Total Energy, 23°C	13	J	ASTM D3763
THERMAL ⁽¹⁾			
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	100	°C	ISO 75/Af
HDT, 1.82 MPa, 3.2mm, unannealed	100	°C	ASTM D648
CTE, -30°C to 30°C, flow	5.20E-05	1/°C	ASTM D696

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -30°C to 30°C, xflow	5.60E-05	1/°C	ASTM D696
PHYSICAL ⁽¹⁾			
Density	1.19	g/cm ³	ISO 1183
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.2 – 0.5	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.4 – 0.7	%	ISO 294
Specific Gravity	1.19	-	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.25	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.2 – 0.5	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.4 – 0.7	%	ASTM D955
INJECTION MOLDING ⁽³⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05 – 0.1	%	
Melt Temperature	260	°C	
Front - Zone 3 Temperature	265 – 275	°C	
Middle - Zone 2 Temperature	230 – 245	°C	
Rear - Zone 1 Temperature	205 – 215	°C	
Mold Temperature	70 – 80	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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